揚博科技股份有限公司
Ampoc Far-East Co., Ltd

2024/09/12
Investor Conference

CONTENTS

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  - Introduction and Prospect

01 Company Profile

Profile

Since 1976

Capital 11.4 Million

Turnover 33.54 Million

Employee 340 people

1976- Establishment

1980-1990

- Ampoc was founded with initial registered capital of NT$1 million;
- TCM Japan established TTCM in CHUNG-LI industrial zone for PCB wet process equipment manufacture. Ampoc invested TTCM and obtained global exclusive distribution ship excluding Japan.

1991-2000

- Ampoc purchased the office in Taipei as headquarters.
- Ampoc was approved as IPO.
- AMPOC merged TTCM.

2001-2010

- Company name changed as “AMPOC FAR-EAST CO., LTD., capital increased to NT$ 0.9 Billion.
- Ampoc (2493) was listed on the Taiwan Stock Exchange on 01/23/2002.

2011-2020

- “Ampoc Wing” was developed and shipped to customer for production usage.
- HK subsidiary was approved by the board of directors.
- AMPOC Shanghai was invested by HK subsidiary.

2021- now

- ESG task force established.
- ECO Heat exchange System developed.
- 2023 new purchase of Nanyuan Road factory for future business development.

02 Company Status

Company status

~AMPOC considers serving customers as its mission, and actively acts as a coordinator for information technology industry~

MR. RONALD SU
(CEO & CHAIRMAN)

2 divisions

- Manufacturing Management Division
- Business Management Division

4 cores

- Advanced manufacture
- Hi-tech R&D
- Advanced semiconductor process
- Energy saving and carbon reduction

9 mindsets

- Quality first
- Innovation
- profession
- Process improvement
- Engagement management
- International marketing
- Service first
- Social responsibility
- Sustainability

3 technologies

- Ampoc Wing
- Ampoc ECO
- Ampoc 5A

03 Financial Information

Financial Information

2022~2024H1Consolidated Balance sheet

Unit: NT$ thousands (Except EPS: NT$)

Item \ Year	2022	2023	2024 H1
Net Revenue	3,448,384	3,354,285	1,762,665
Gross profit	1,098,413	1,219,708	628,990
Gross margin(%)	31.85	36.36	35.68
Operating income	756,369	836,161	430,027
Net income after tax	592,400	690,310	349,703
EPS	5.18	6.03	3.06

Financial Information

2022~2024H1 Consolidated Income statement

Unit: NT$ thousands (Except EPS: NT$)

Item \ Year	2022	2023	2024 H1
Current Assets	3,992,366	3,869,784	3,839,798
Non-current Assets	633,581	1,113,823	1,124,581
Total Assets	4,625,947	4,983,607	4,964,379
Current Liabilities	1,762,805	1,709,646	1,979,219
Non-current Liabilities	98,176	273,407	198,822
Total Liabilities	1,860,981	1,983,053	2,178,041

Financial Information

2022~2024H1 Financial Analysis

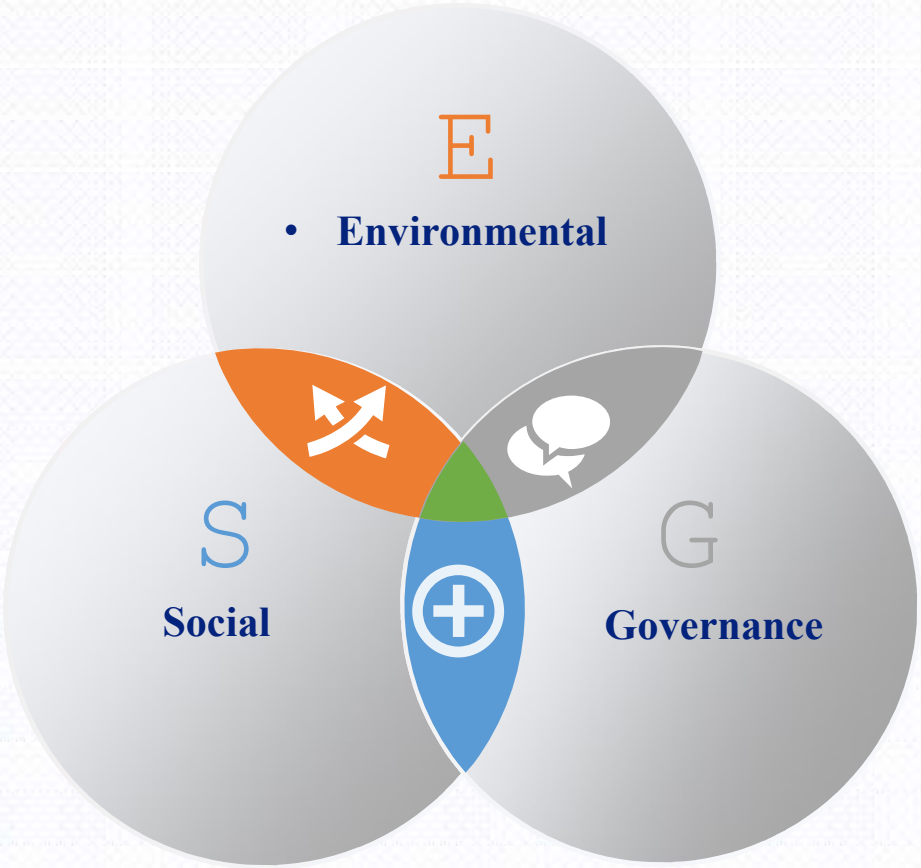
Item / Year	2022	2023	2024 H1
Debt Ratio(%)	40.23	39.79	43.87
Current Ratio(%)	226.48	226.35	194.00
Average Inventory Turnover(Times)	1.91	1.86	2.19
Return on Equity (%)	22.76	23.95	12.09

04

Own Brand Equipment - Introduction and Prospect

04 Own Brand Equipment Introduction

ESG



Patents on ECO System

実用新案登録証
(CERTIFICATE OF UTILITY MODEL REGISTRATION)

登録第３２４２４６２号
(REGISTRATION NUMBER)

考案の名称 (TITLE OF THE DEVICE): 回路基板製造プロセス用の熱交換システム

実用新案権者 (OWNER OF THE UTILITY MODEL RIGHT): 台湾台北市信義區松德路１７１號１７樓
国籍・地域 台湾
揚博科技股ふん有限公司

考案者 (CREATOR OF DEVICE): 蘇 勝義
巫 坤星
呂 理榕

その他別紙記載

出願番号 (APPLICATION NUMBER): 実願２０２３－００１２８４
出願日 (FILING DATE): 令和 ５年 ４月１７日(April 17, 2023)
登録日 (REGISTRATION DATE): 令和 ５年 ６月１２日(June 12, 2023)

この考案は、登録するものと確定し、実用新案原簿に登録されたことを証する。
(THIS IS TO CERTIFY THAT THE UTILITY MODEL IS REGISTERED ON THE REGISTER OF THE JAPAN PATENT OFFICE.)

令和 ５年 ６月１２日(June 12, 2023)

特許庁長官
(COMMISSIONER, JAPAN PATENT OFFICE)

濱野幸一

证书号第17480510号

实用新型专利证书

实用新型名称：电路板制程的热交换系统

发 明 人：苏胜義;巫坤星;吕理榕;苏绍君;钟添达;杨延鸿

专 利 号：ZL 2022 2 1538110.X

专利申请日：2022年06月20日

专 利 权 人：扬博科技股份有限公司

地 址：中国台湾台北市

授权公告日：2022年09月27日 授权公告号：CN 217509142 U

国家知识产权局依照中华人民共和国专利法经过初步审查，决定授予专利权，颁发实用新型专利证书并在专利登记簿上予以登记。专利权自授权公告之日起生效。专利权期限为十年，自申请日起算。

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局长
申长雨

国家知识产权局

2022年09月27日

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其他事项参见续页

中華民國專利證書

新型第 M634845 號

新型名稱：電路板製程的熱交換系統

專利權人：揚博科技股份有限公司

新型創作人：蘇勝義、巫坤星、呂理榕、蘇紹君、鍾添達、楊延鴻

專利權期間： 自2022年12月1日至2032年6月15日止

上開新型業依專利法規定通過形式審查取得專利權
行使專利權如未提示新型專利技術報告不得進行警告

經濟部智慧財產局 局長 洪淑敏

中華民國 111 年 12 月 1 日

注意：專利權人未依法繳納年費者，其專利權自原繳費期限屆滿後消滅。

ECO System video

Patents on Ampoc Pure

実用新案登録証
(CERTIFICATE OF UTILITY MODEL REGISTRATION)

登録第３２４２５７７号
(REGISTRATION NUMBER)

考案の名称 (TITLE OF THE DEVICE): 二重濾過循環システム

実用新案権者 (OWNER OF THE UTILITY MODEL RIGHT): 台湾台北市信義區松德路１７１號１７樓
国籍・地域　台湾
揚博科技股ふん有限公司

考案者 (CREATOR OF DEVICE): 蘇　勝義
巫　坤星
呂　理榕

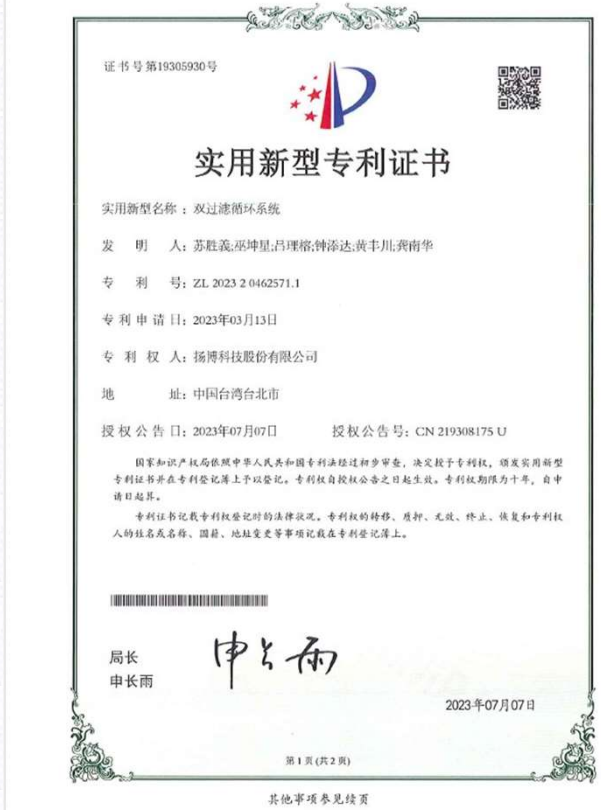
その他別紙記載

出願番号 (APPLICATION NUMBER): 実願２０２３－００１４３２
出願日 (FILING DATE): 令和　５年　４月２６日(April 26, 2023)
登録日 (REGISTRATION DATE): 令和　５年　６月１５日(June 15, 2023)

この考案は、登録するものと確定し、実用新案原簿に登録されたことを証する。
(THIS IS TO CERTIFY THAT THE UTILITY MODEL IS REGISTERED ON THE REGISTER OF THE JAPAN PATENT OFFICE.)

令和　５年　６月１５日(June 15, 2023)

特許庁長官 (COMMISSIONER, JAPAN PATENT OFFICE)
濱野幸一



证书号第19305930号

实用新型专利证书

实用新型名称：双过滤循环系统

发　明　人：苏胜义;巫坤星;吕理榕;钟添达;黄丰川;龚南华

专　利　号：ZL 2023 2 0462571.1

专利申请日：2023年03月13日

专　利　权　人：扬博科技股份有限公司

地　　址：中国台湾台北市

授权公告日：2023年07月07日　　授权公告号：CN 219308175 U

国家知识产权局依照中华人民共和国专利法经过初步审查，决定授予专利权，颁发实用新型专利证书并在专利登记簿上予以登记。专利权自授权公告之日起生效。专利权期限为十年，自申请日起算。

专利证书记载专利权登记时的法律状况。专利权的转移、质押、无效、终止、恢复和专利权人的姓名或名称、国籍、地址变更等事项记载在专利登记簿上。

局长
申长雨

2023年07月07日

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其他事项参见续页

中華民國專利證書

新型第　M643395　號

新型名稱：雙過濾循環系統

專利權人：揚博科技股份有限公司

新型創作人：蘇勝義、巫坤星、呂理榕、鍾添達、黃豐川、龔南華

專利權期間：自2023年7月1日至2033年3月8日止

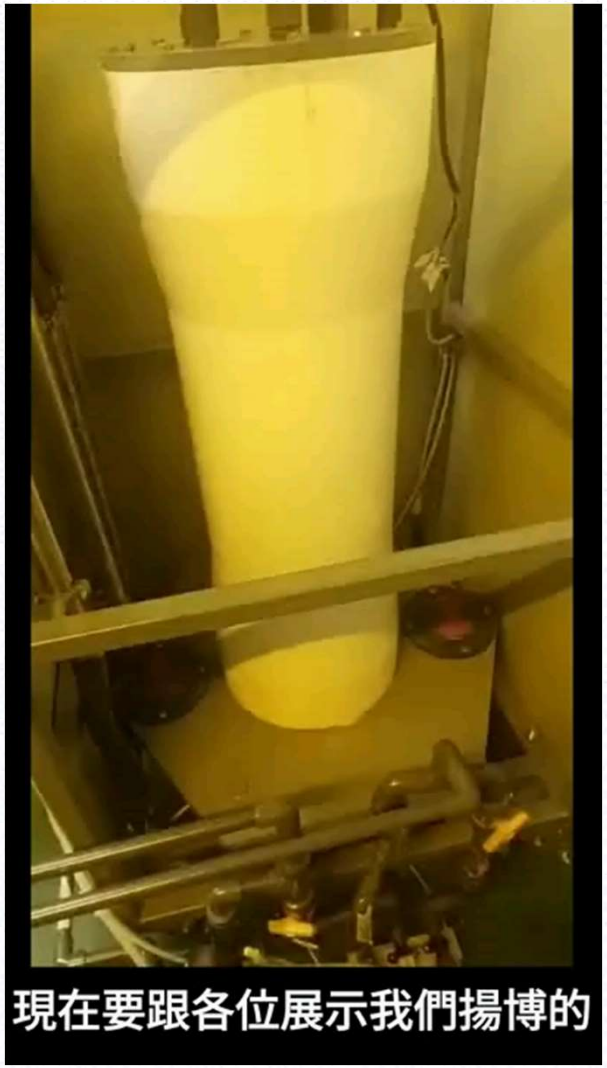
上開新型業依專利法規定通過形式審查取得專利權
行使專利權如未提示新型專利技術報告不得進行警告

經濟部智慧財產局 局長
廖承威

中華民國 112 年 7 月 1 日

注意：專利權人未依法繳納年費者，其專利權自原核准期限屆滿後消滅。

Ampoc Pure Purification System



Own Brand Equipment
- Retrospect and Prospect

2024 H1 Retrospect and Prospect

1. In the first half of 2024, the primary self-manufactured equipment usage will be focused on substrates and HDI, and there is a significant proportion in substrate-like applications. The market applications include smartphones, automotive electronics, servers, and other product markets.
2. The Ampoc 7A (Arrows) patented new product will be launched, which will be publicly presented at TPCA from Oct. 23-25 this year. Besides addressing glass substrate equipment, the two patented designs, the ECO heat recovery system and the Ampoc PURE purification system, contribute significantly to energy saving and carbon reduction in response to global warming trends.
3. In response to customers moving their factories to Southeast Asia, we are progressively installing equipment and will establish a service point in Thailand to closely communicate with customers, provide after-sales service, and seize business opportunities.

2024 H1 Retrospect and Prospect

Future Equipment Development and Demand Outlook:

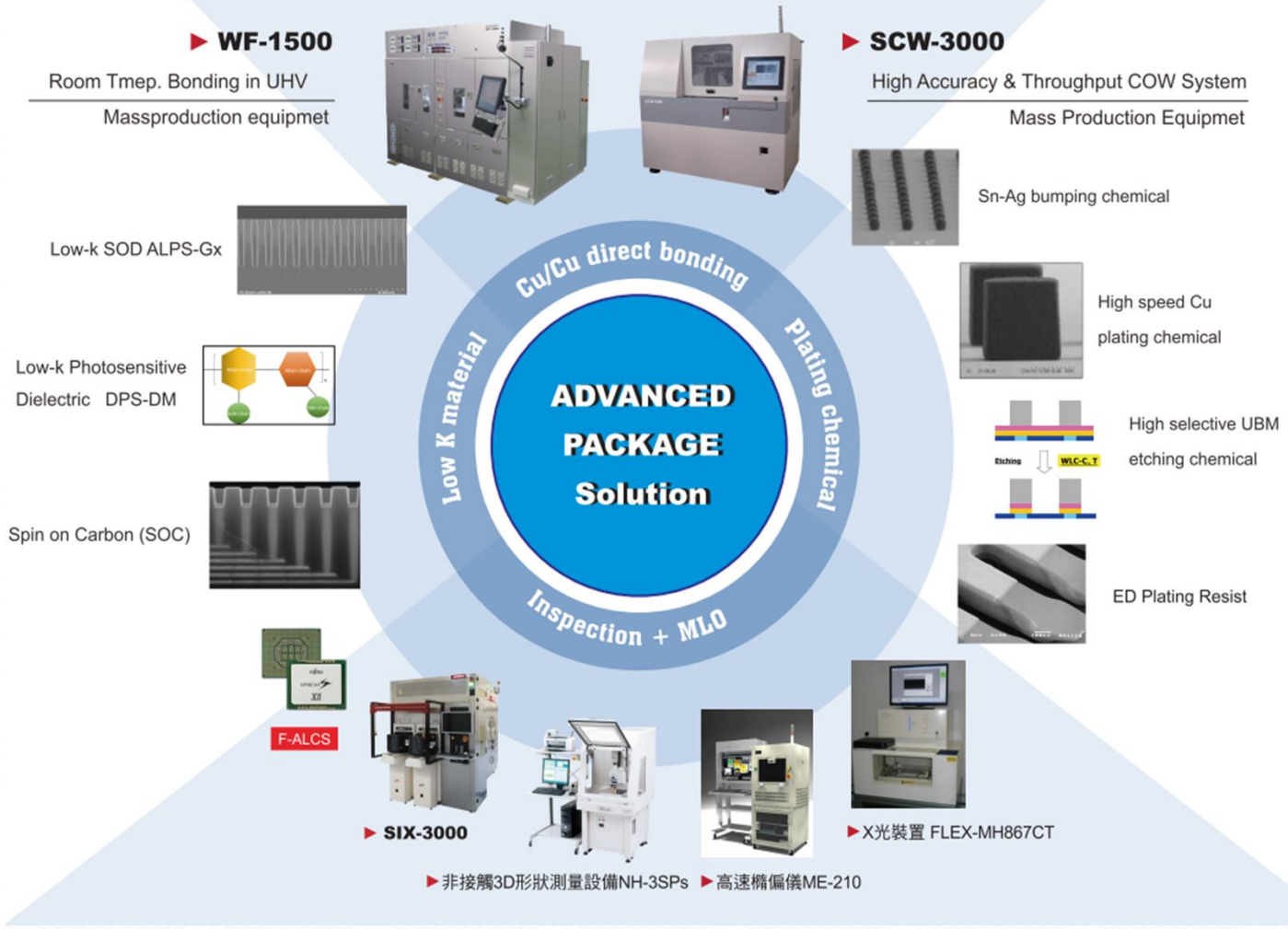
1. High-end Process Equipment for ABF Substrates and Glass Substrates.
2. Competition in High-end Products among PCB Manufacturers, including 5G-related substrates, substrate-like materials, HDI, and flexible PCB equipment.
3. Demand for PCB Equipment related to Electric Vehicles and Safety.
4. Ongoing Development of Energy-saving, Waste-reducing, and Dust-free Equipment.

05 Distribution Business

- Introduction and Prospect

Target & Planning

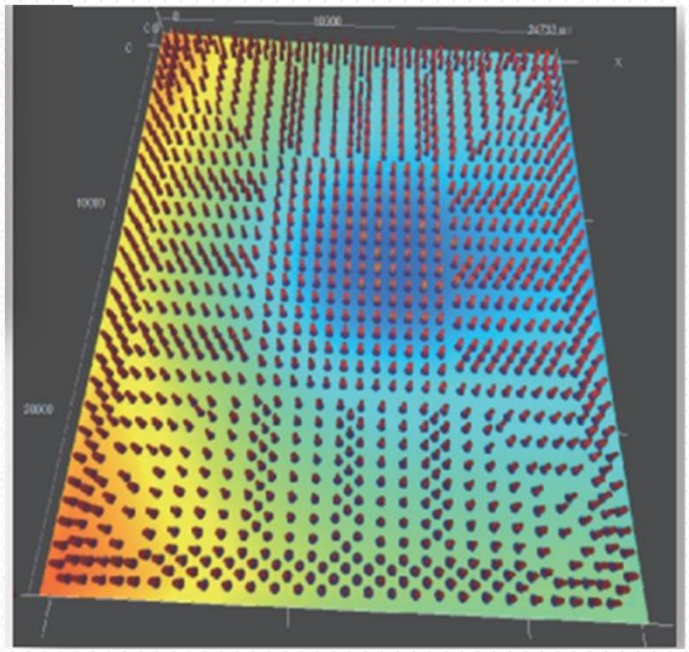
Advance package/Material/Inspect solution

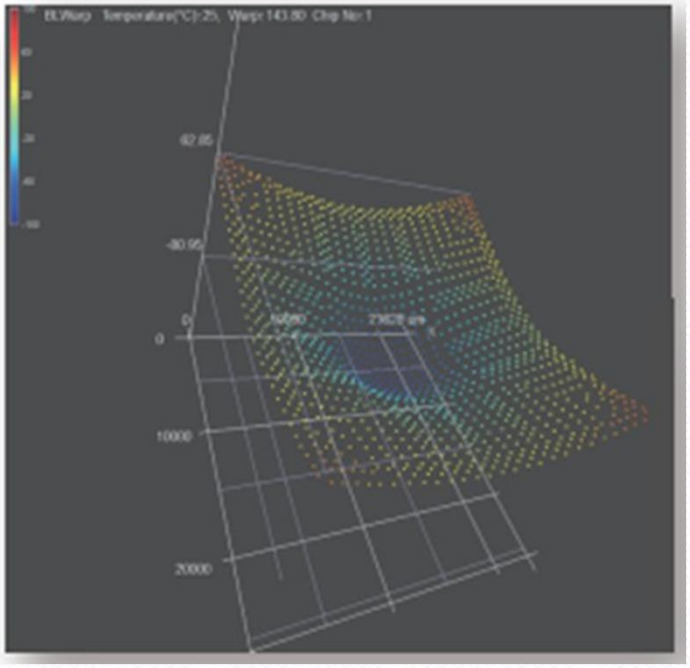


Target & Planning

- 3D Measurement Equipment

Function: Used for morphology measurement before bonding.
Purpose: Variations occur during advanced packaging processes. This equipment provides a large amount of morphological data after measurement, significantly improving bonding yield.

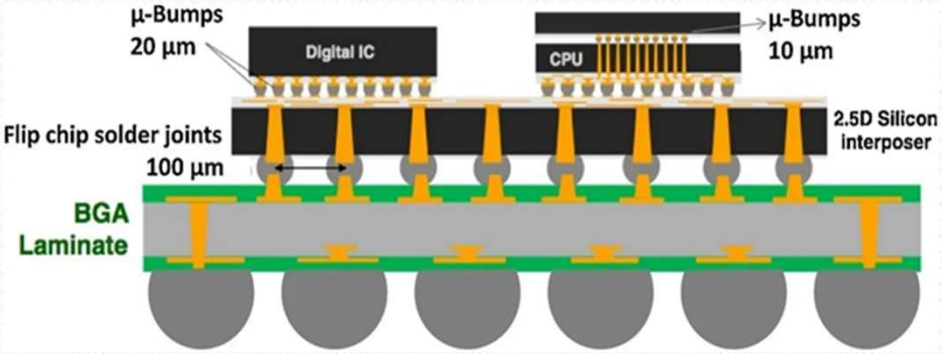




Target & Planning

Material

- Advanced PKG
  - Micro Bumping/SnAg (Mass production now)
  - Cu Pillar(Mass production now)
  - Dielectric (developing)
- **Semicon Front-end materials**
  - Lithograph material
  - Domestic/foreign factories are now testing

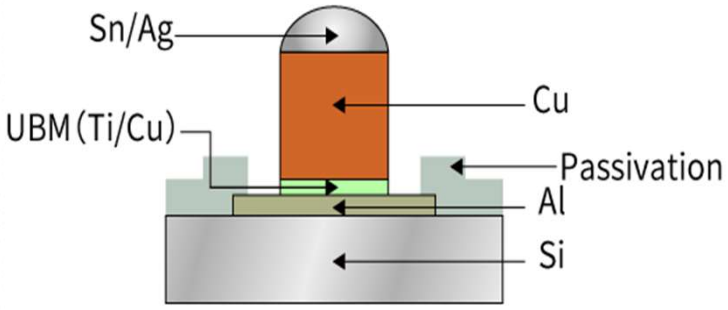


2.5D/3D IC 封裝結構的橫截面圖

資料來源:https://www.eettaiwan.com/20221220nt41-3d-ic-ma-tek/

Equipment

- **AI**
  - 2.5D Bonder (validation in progress)
  - 3D Bonder (End customer product is undergoing final validation)
  - 3D Bonding Inspection Machine



資料來源：https://www.shinko.co.jp/english/product/package/assembly/cu-pillar.php

Process Application

- Chip On Wafer on Substrate
- HPC
- Si Photonics

AI

- FOPLP (Fen Out Panel Level Package)

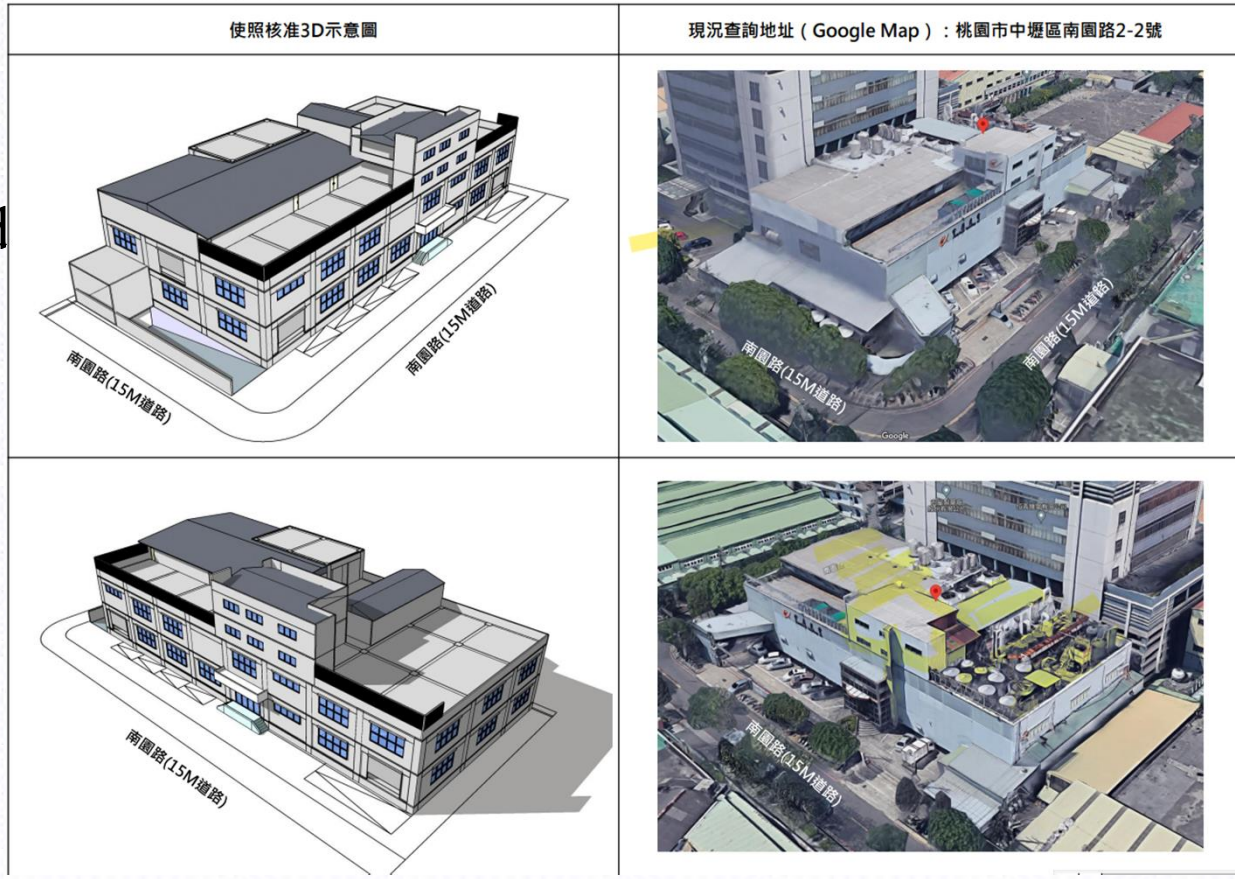
2023-2024 Retrospect and Prospect

- Revenue from advanced semicon PKG by the operations division has benefited from the growth in AI demand, with significant improvements observed in high-end packaging, photolithography processes, and overseas markets.

- Revenue comparison H1 2023 vs H1 2024 ：
  - High-end packaging grew by 15%；
  - Photolithography materials grew by 64%；
  - By sales region: Taiwan increased by 31%, while overseas regions grew by 8%.

2023-2024 Retrospect and Prospect

- 2023 - new Zhongli factory building (as shown in the image on the right) was purchased for operation need and future market layout planning.
- 2024 August - The factory license and factory registration were completed.
- 2024~2025 - The factory renovation and repairs are scheduled.



圖：中壢工業區新購廠房

Thank you for your Attention!